**HIGHEST THERMAL CONDUCTIVITY SILICONE-FREE GAP FILLER AVAILABLE**

Tflex™ SF800 is a high-performance, compliant, silicone free thermal interface material. By coupling extremely high thermal conductivity with exceptional wetting characteristics, Tflex™ SF800 provides some of the lowest thermal resistance values in the industry. This makes it well-suited for applications where silicone based pads are traditionally used as well as those applications which are silicone sensitive.

Tflex™ SF800 is naturally tacky on both sides requiring no additional adhesive coating, which would inhibit thermal performance. The natural tack allows for the pad to be held in place during assembly.

**FEATURES AND BENEFITS**

- Silicone-free gap pad
- Thermal Conductivity of 7.8 W/mK
- Exceptionally low thermal resistance
- Available in thicknesses from 0.020-inch (0.50mm) through 0.040-inch (1.00mm) in 0.010-inch increments
- RoHS Compliant

APPLICATIONS

- Silicone-sensitive applications
- Automotive applications
- Optical components
- Flat panel displays
- Hard disk drives
- Medical devices
- Laser equipment
- Aerospace electronics
- Solar energy

global solutions: local support.™

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Tflex™ SF800 TYPICAL PROPERTIES

	Tflex™ SF800	TEST METHOD
Construction	Ceramic-filled, silicone-free gap filler	N/A
Color	Grey	Visual
Thermal Conductivity (W/mK)	7.8	Hot Disk
Thermal Resistance at 30 mil bondline (°Cin ² /W)	0.19	ASTM D5470 (modified)
Thickness Range (inches / mm)	0.020 - 0.040 / 0.50 - 1.00	
Thickness Tolerance (%)	± 10	
Density (g/cc)	3.21	Helium Pycnometer
Hardness (Shore 00)	81 ; 3 seconds 75 ; 30 seconds	ASTM D2240
Volatile Siloxane (D3-D10)	None detected*	GC/MS
Weight Loss over time @ 120°C, 168 hrs (%)	< 0.2	TGA
Belcore (Telcordia) Silicone Extraction	Pass	TR-NWT-000930
UL Flammability Rating (UL 94)	V0**	File E180840
Continuous Use Temperature (°C)	-20 to 120	TGA
CTE (ppm/°C)	106.1; 25°C to 120°C	IPC-TM-650 2.4.24
Heat Capacity at 50°C (J/g-K)	0.8	MDSC
Volume Resistivity (ohm-cm)	5 x 10 ¹²	ASTM D257
Dielectric Constant @ 1 kHz	16.6	ASTM D150
@ 1 MHz	15.9	
Dissipation Factor @ 1 kHz	0.09	ASTM D150
@ 1 MHz	0.03	

* Method detection limit = 40ppm ** Pending

STANDARD THICKNESSES

Standard thickness is 0.020-inch (0.50 mm) through 0.040-inch (1.00mm) in 0.010-inch increments

OPTIONS

Material is standard with both sides tacky;

MATERIAL NAME AND THICKNESS

Tflex™ indicates Laird Technologies' gap filler product line. SF8XXX indicates Tflex™ SF800 product line with thickness in mils (0.001-inches)

Examples:

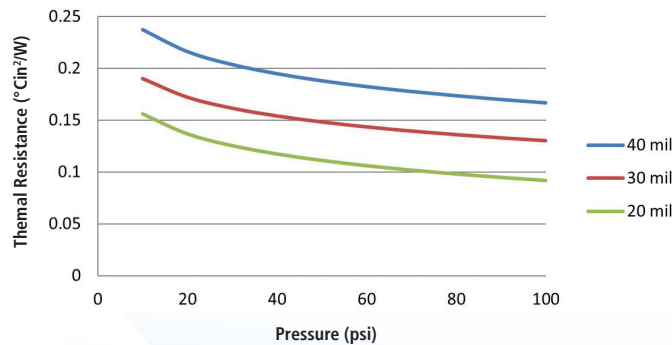
Tflex™ SF840 = standard 0.040-inch thick Tflex™ SF800 material

Data for design engineer guidance only.

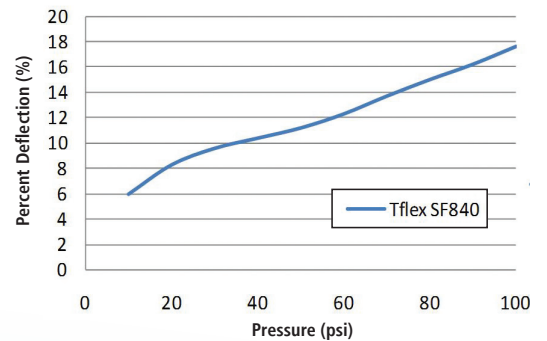
Observed performance varies in application.

Engineers are reminded to test the material in application

Thermal Resistance vs Pressure



Percent Deflection vs Pressure



THR-DS-Tflex-SF800 1112

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